502210699 01/29/2013

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Yu HARUBEPPU	11/20/2012
Takayuki KUSHIMA	11/22/2012
Yasuhiro NEMOTO	11/22/2012
Keisuke HORIUCHI	11/21/2012
Hisashi TANIE	11/20/2012

RECEIVING PARTY DATA

Name:	Hitachi, Ltd.	
Street Address:	6-6, Marunouchi 1-chome	
City:	Chiyoda-ku, Tokyo	
State/Country:	JAPAN	

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	13689299

CORRESPONDENCE DATA

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Correspondence will be sent via US Mail when the fax attempt is unsuccessful.

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ATTORNEY DOCKET NUMBER:	029118.65145US
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NAME OF SUBMITTER: Michael H. Jacobs

Total Attachments: 1

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REEL: 029710 FRAME: 0116

ASSIGNMENT (譲渡証)

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration pald to me, citizen of Japan, by Hitachi, Ltd., a corporation organized under the laws of Japan, located at 6-6, Marunouchi 1-chome, Chiyoda-ku, Tokyo, Japan, receipt of which is hereby acknowledged, I do hereby sell and assign to said Hitachi, Ltd., its successors and assigns, all my right, title and interest, in and for the United States of America, in and to

POWER SEMICONDUCTOR DEVICE

invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted, to be held and enjoyed by said Hitachi, Ltd., its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted, as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said Hitachi, Ltd..

Signed on the date(s) indicated aside signatures:

	INVENTOR(S) (発明者フルネームサイン)	Date Signed (署名日)
1)	Ju Horenbeppu	11/20/2012
·	Yu HARUBEPPU	
2)	Jakayuki Kushima Takayuki KUSHIMA	11/22/2012
3)	Yasuhivo Nemoto Yasuhiro NEMOTO	11/22/2012
4)	Herisch Horinshi	11/21/2012
	Keisuke HORIUCHI	
5)	Hisashi Tanie	11/20/2012
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